

General Description

The WST2028 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent R_{DSON} and gate charge for most of the small power switching and load switch applications.

The WST2028 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

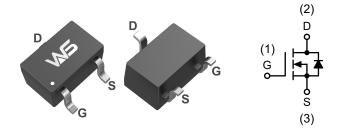
Product Summery

BV _{DSS}	R _{DSON}	Ι _D
20V	50mΩ	2.1A

Applications

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT-323-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	20	V
V _{GS}	Gate-Source Voltage	±8	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	2.1	A
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	1.1	А
I _{DM}	Pulsed Drain Current ²	8.2	A
P _D @T _A =25℃	Total Power Dissipation ³	0.35	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹		357	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		135	°C/W



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V	
∆BV _{DSS} /∆T _J	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!{\rm C}$, I_D=1mA		0.022		V/℃	
Р	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =2A		50	60	mΩ	
R _{DS(ON)}		V _{GS} =2.5V , I _D =1A		70	90		
V _{GS(th)}	Gate Threshold Voltage		0.5	0.7	1.2	V	
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_{D}=250$ uA		-2.33		mV/℃	
		V _{DS} =16V , V _{GS} =0V , T _J =25℃			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =55℃			5	- uA	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =2A		12		S	
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		6.0		Ω	
Qg	Total Gate Charge (4.5V)			5.0			
Q _{gs}	Gate-Source Charge	V_{DS} =10V , V_{GS} =4.5V , I_{D} =2A		0.8		nC	
Q _{gd}	Gate-Drain Charge			1.7			
T _{d(on)}	Turn-On Delay Time	N/ 401/		3.2			
Tr				12			
T _{d(off)}	Turn-Off Delay Time	V_{GS} =4.5V , R _G =6 Ω		4		ns	
T _f	Fall Time	I _D =1A		26			
C _{iss}	Input Capacitance			300			
C _{oss}	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		57		pF	
Crss	Reverse Transfer Capacitance			47			

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,4}				2.1	А
I _{SM}	Pulsed Source Current ^{2,4}	$V_G = V_D = 0V$, Force Current			8.0	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.3	V
t _{rr}	Reverse Recovery Time			10		nS
Q _{rr}	Reverse Recovery Charge	l ⊧=2A , dl/dt=100A/µs , T _J =25℃		3.2		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10 sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The power dissipation is limited by 150 $^\circ C$ junction temperature

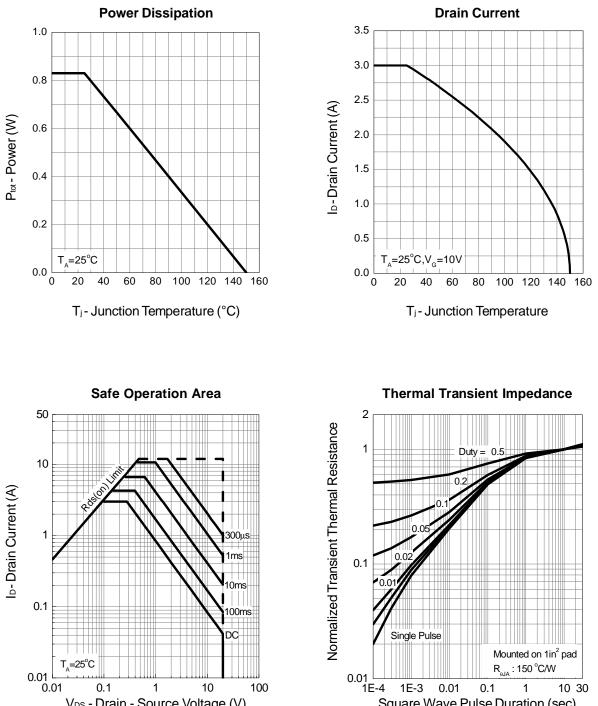
4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



WST2028

N-Channel MOSFET

Typical Characteristics

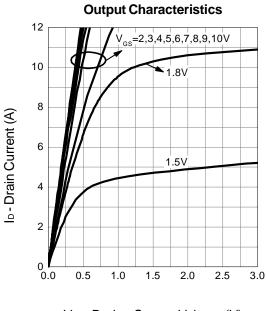


Square Wave Pulse Duration (sec)

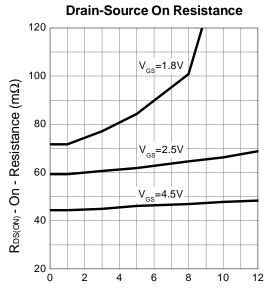
V_{DS} - Drain - Source Voltage (V)



Typical Characteristics



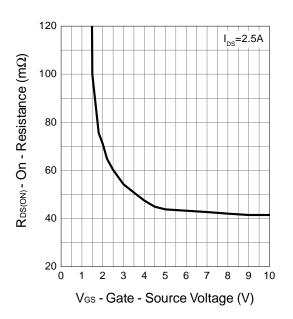
VDS-Drain - Source Voltage (V)

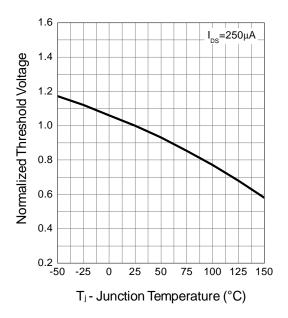


ID-Drain Current (A)

Gate-Source On Resistance

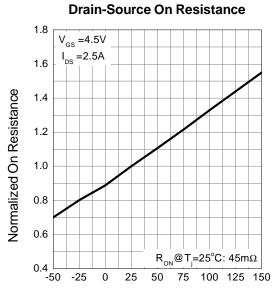
Gate Threshold Voltage



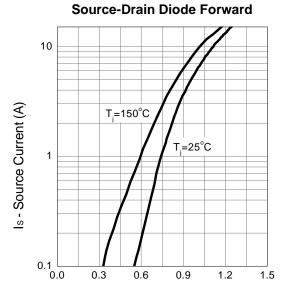




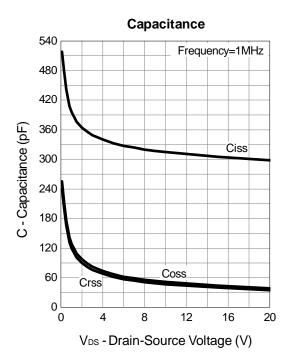
Typical Characteristics

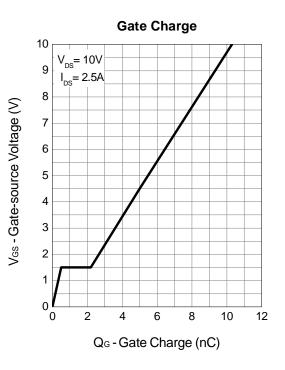


T_j-Junction Temperature (°C)



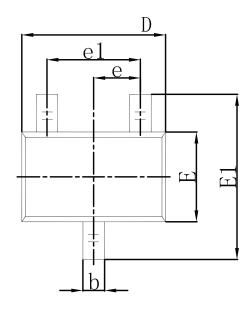
Vsp - Source - Drain Voltage (V)

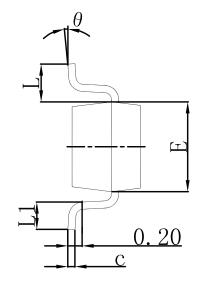


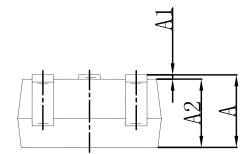




Packaging information







Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Мах	Min	Мах	
A	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.200	0.400	0.008	0.016	
С	0.080	0.150	0.003	0.006	
D	2.000	2.200	0.079	0.087	
E	1.150	1.350	0.045	0.053	
E1	2.150	2.450	0.085	0.096	
е	0.65	0.650 TYP		TYP	
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021	REF	
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	



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